

BAL-CW1250D3

Balun transformer with integrate matching

Datasheet – production data



Features

- 50 Ω nominal input / match ST-Ericsson RF IC CW1250, CW1150, CW1260
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- DC blocking access on single RF input
- Small footprint: < 1.2 mm²

Benefits

- Extremely low profile (< 550 µm after reflow)
- Integrate matching network
- High RF performances
- RF components count and area reduction

Applications

• Balun with integrated matching for ST-Ericsson RF IC CW1250, C1150, CW1260

Description

STMicroelectronics BAL-CW1250D3 is a balun (balanced/unbalanced device) designed to transform a single ended signal to differential signals in WLAN application. This BAL-CW1250D3, with low insertion losses in the brandwidth 2400 MHz to 2500 MHz, has been customized for CW1250, CW1150, CW1260 tranceiver. The differential output embeds an integrated matching network adapted to the transceiver.

The BAL-CW1250D3 has been designed using STMicroelectronics IPD (integrated passive device) technology on non-conductive glass substrate to optimize RF performances.

Figure 1. Pinout diagram (top view)



This is information on a product in full production.

1 Characteristics

Symbol	Parameter		Value		
Symbol			Тур	Max	Onit
P _{IN}	Average power RF _{IN}			24	dBm
	ESD ratings MIL STD883C (HBM: C = 100 pF, R = 1.5 k Ω , air discharge)	2000			
V _{ESD}	ESD ratings charged device model (JESD22-C101-D)	500			V
	ESD ratings machine model (MM: C = 200 pF, R = 25 Ω , L = 500 nH)	200			
T _{OP}	Operating temperature	-30 to +85		°C	

Table 1. Absolute maximum ratings (limiting values)

Table 2. Impedances (T_{amb} = 25 °C)

Symbol	Symbol Parameter Min		Value		
Gymbol			Тур	Max	Onic
Z _{OUT}	Nominal differential output impedance		matched		Ω
Z _{IN}	Nominal input impedance		50		Ω

Table 3. RF performance (T_{amb} = 25 °C)

Symbol	Parameter		Value		
			Тур	Max	Onit
F	Frequency range (bandwidth)	2400		2500	MHz
IL	Insertion loss in bandwidth		0.97		dB
RL _{SE}	Single ended return loss in bandwidth -21		dB		
RL _{DIFF}	Differential return loss in bandwidth -24			dB	
φimb	Phase imbalance	-10		10	0
Aimb	Amplitude imbalance	-1	0.1	1	dB
Att _{2f0}	2nd harmonic attenuation		-19		dB









Figure 6. Phase imbalance







Figure 7. Second harmonic attenuation

2 Application information





3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.







Figure 11. Marking





Figure 12. Recommended land pattern (used for balun characterization)







More information is available in the application notes: AN2348 Flip-Chip package description and recommendations for use



4 Ordering information

Table 4. Ordering i	information
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Part Number	Marking	Package	Weight	Base Qty	Delivery Mode
BAL-CW1250D3	SG	Flip Chip	1.46 mg	5000	Tape and Reel(7")

5 Revision history

	Table 5	. Document	revision	history
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Date	Revision	Changes
23-May-2013	1	Initial release.



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